



WOM Material Safety Data Sheet

Material Content Declaration					
Material name	Substance name e.g. Copper (Cu)	CAS no., if known	Substance mass (mg)	% OF Weight (%)	ppm Of Total Weight
Lead Wire 59.11%	Copper (Cu)	7440-50-8	673.199	99.9791	591,010.2
	Phosphorus (P)	7723-14-0	0.007	0.0010	6.1
	Arsenic (As)	7440-38-2	0.007	0.0010	6.1
	Tin (Sn)	7440-31-5	0.007	0.0010	6.1
	Oxygen (O)	7782-44-7	0.003	0.0004	2.6
	Sulfur (S)	7704-34-9	0.082	0.0122	72.0
	Iron (Fe)	7439-89-6	0.004	0.0006	3.5
	Nickel (Ni)	7440-02-0	0.002	0.0003	1.8
	Bismuth (Bi)	7440-69-9	0.012	0.0018	10.5
	Antimony (Sb)	1309-64-4	0.012	0.0018	10.5
	Lead (Pb)	7439-92-1	0.003	0.0004	2.6
	Zinc (Zn)	7440-66-6	0.002	0.0003	1.8
	Total		673.34		
Solder Wafer 0.73%	Lead (Pb)	7439-92-1	7.78	93.29	6,830.2
	Tin (Sn)	7440-31-5	0.36	4.31	316.0
	Silver (Ag)	7440-22-4	0.20	2.40	175.6
	Total		8.34		
Chip 0.60%	Silicon (Si)	7440-21-3	6.49	95.40	5,695.2
	Lead (Pb)	7439-92-1	0.31	4.60	274.6
	Total		6.80		
Case 13.70%	Epoxy	38891-59-7	156.80	100.00	137,656.8
	Total		156.80		
Potting 25.30%	Epoxy	38891-59-7	288.20	100.00	253,014.5
	Total		288.20		
Plating 0.56%	Silver (Ag)	7440-22-4	5.59	100.00	4,903.1
	Total		5.59		
	Total mass (mg)		1,139.07		